

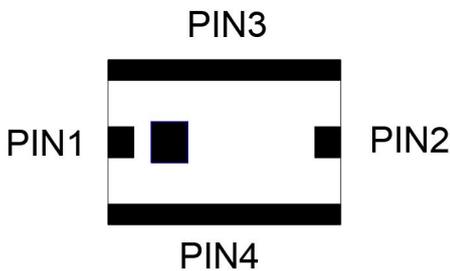
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

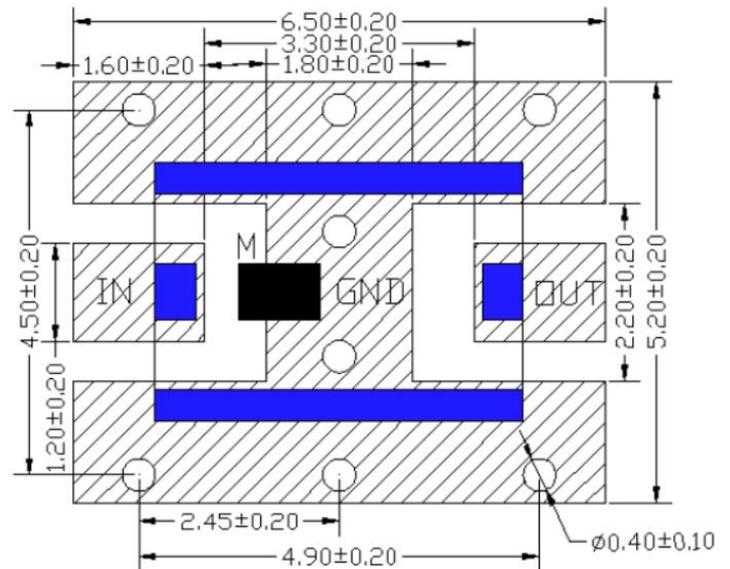
| NO. | Parameter | Frequency (MHz) | SPEC | |
|-----|----------------------------------|-----------------|------|------|
| | | | Min. | Max. |
| 1 | Insertion Loss (dB) | 2000~3500 | | 3.0 |
| 2 | Attenuation (dB) | 1750 | 28 | |
| | | 4000 | 28 | |
| 3 | VSWR | 2000~3500 | | 2.0 |
| 4 | In/Output Impedance (Ω) | | 50 | |

Construction



| PIN | Connection |
|-----|-------------|
| 1 | Input Port |
| 2 | Output Port |
| 3 | GND |
| 4 | GND |

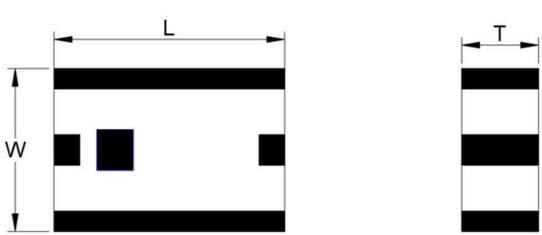
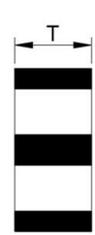
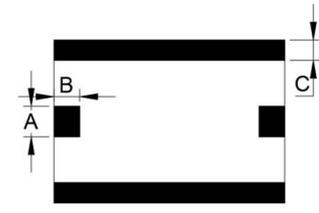
Mounting Considerations



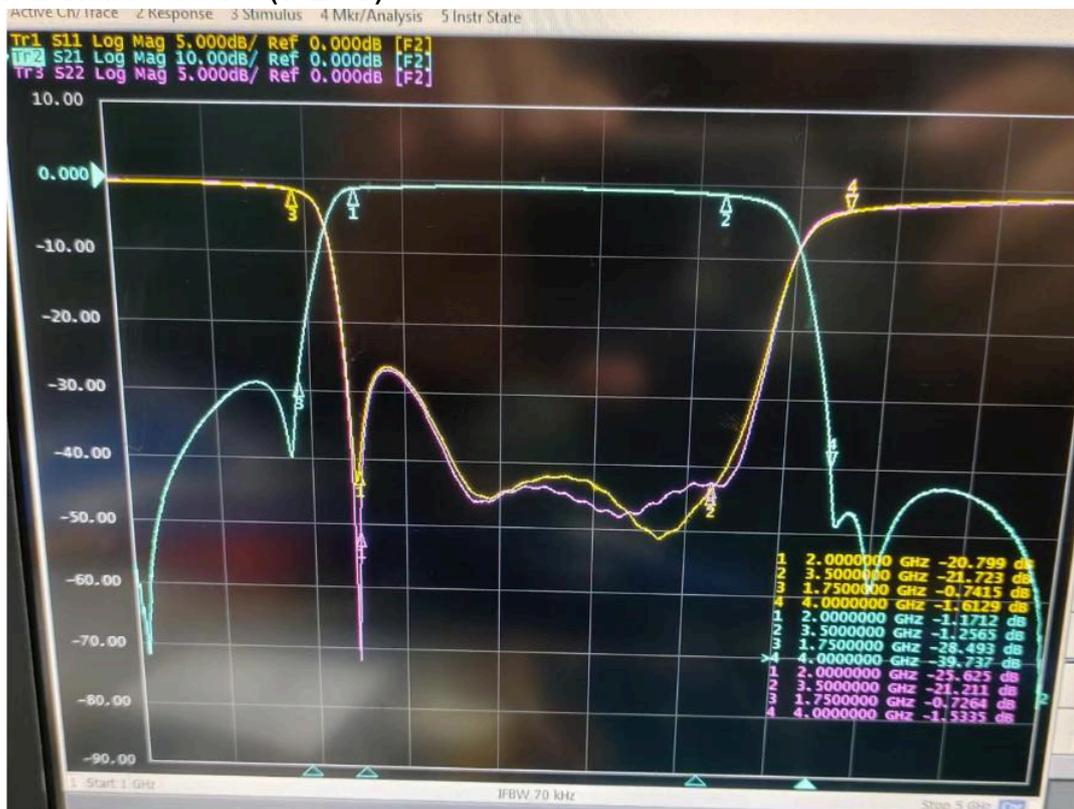
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

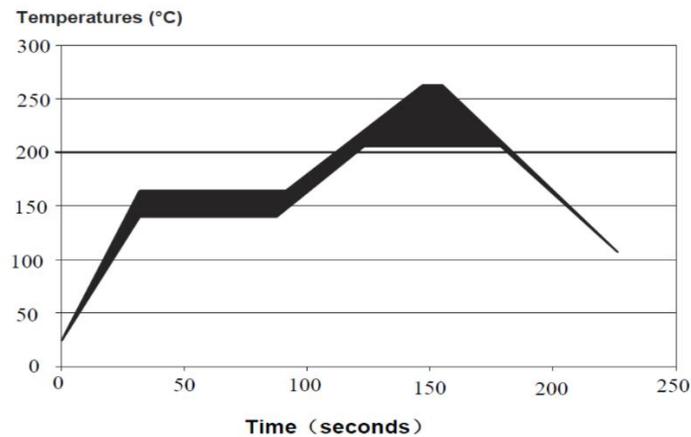
Dimensions

| Figure | Symbol | Dimension (mm) |
|--|--------|----------------|
|  | L | 4.50±0.20 |
| | W | 3.20±0.20 |
|  | T | 1.50±0.20 |
| | A | 0.60±0.10 |
|  | B | 0.50±0.10 |
| | C | 0.40±0.10 |

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.